


FORM PTO-1449	Docket No.: 1431.168.101	Serial No.: 10/588,927
 1st OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Applicant: Irwin Aberin et al.	
	Filing Date: August 9, 2006	Group Art:

U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
/M.J./	AA 6,014,318	01/11/2000	Takeda	*****	*****	
/M.J./	AB 6,054,755	04/25/2000	Takamichi et al.	*****	*****	
/M.J./	AC 6,285,086	09/04/2001	Sota et al.	*****	*****	
/M.J./	AD 2001/0042908	11/22/2001	Okada et al.	*****	*****	
/M.J./	AE 2002/0076858	06/20/2002	Dotta et al.	*****	*****	
	AF					
	AG					
	AH					
	AI					
	AJ					
	AK					
	AL					

FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Class	Sub Class	Translated Yes No
/M.J./	AM JP03283453	12/13/1991	Japan	*****	*****	Yes (Abstract only)
/M.J./	AN KR2002016126	03/04/2002	Korea	*****	*****	Yes (Abstract only)
/M.J./	AO KR2002064592	08/09/2002	Korea	*****	*****	Yes (Abstract only)

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

/M.J./	AR	Wong et al., "Advanced Moisture Diffusion Modeling & Characterisation for Electronic Packaging", 2002 Electronic Components and Technology Conference, 0-7803-7430-4/02/\$17.00 ©2002 IEEE.
/M.J./	AS	Wong et al., "The Mechanics and Impact of Hygroscopic Swelling of Polymeric Materials in Electronic Packaging", Electronic Components and Technology Conference, 0-7803-5911-9/00/\$10.00 (c)2000 IEEE
	AT	

EXAMINER: /Michael Jung/

DATE CONSIDERED: 04/13/2009

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.